

FEATURES

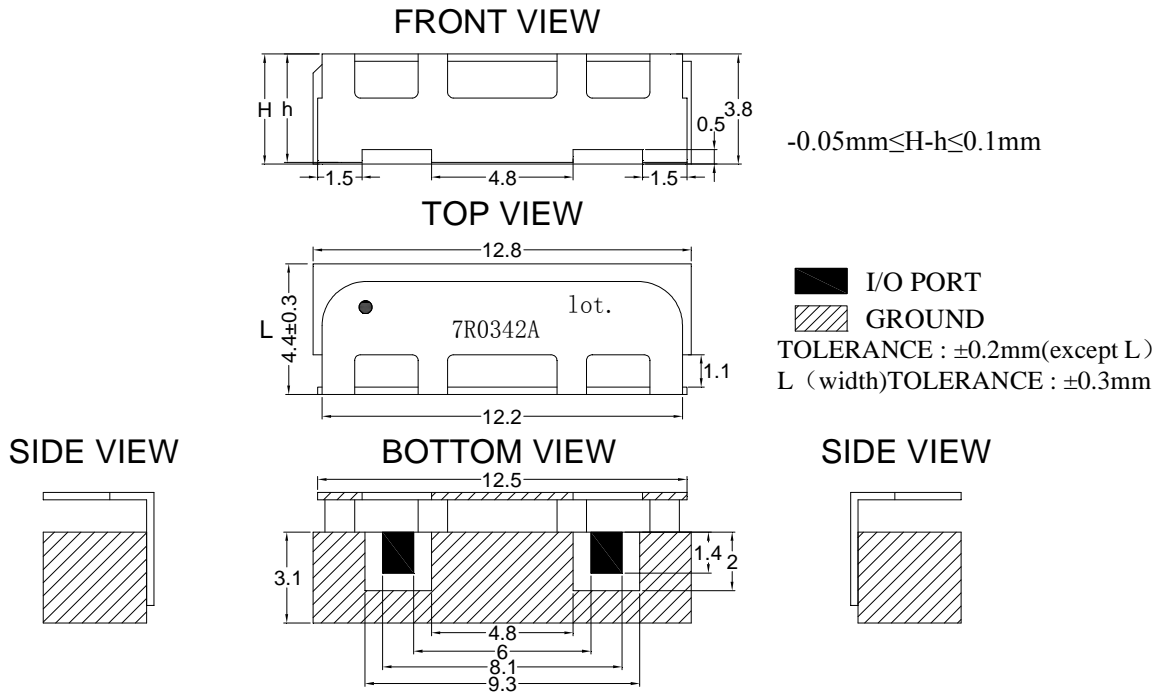
- Small Size,Light weight
- SMT package soldering
- Ideal for Microwave telecommunication

SPECIFICATIONS

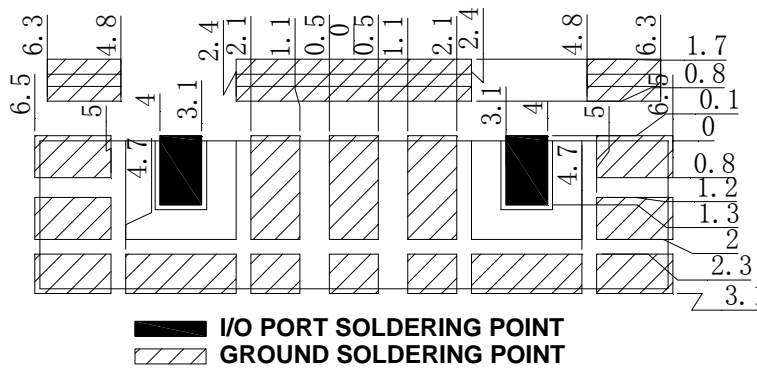
NO.	ITEM	Spec			UNIT	
		Min	Typ	Max		
1	Center Frequency	5170	5502.5	5835	MHz	
2	Bandwidth [BW]	/	665	/	MHz	
3	Insertion Loss @ 5170~5825MHz	/	/	2.5	dB	
	Insertion Loss @ 5825~5835MHz	/	/	3		
4	Ripple in BW (any 320MHz)	/	/	2.3	dB	
5	VSWR in BW	/	/	2.0	/	
6	Attenuation [Absolute Value]	@30~2500MHz	35	/	/	dB
		@2512~3600MHz	30	/	/	
		@3800~4200MHz	30	/	/	
		@4800~4900MHz	25	/	/	
		@5935~6200MHz	45	49	/	
		@6200~7125MHz	50	/	/	

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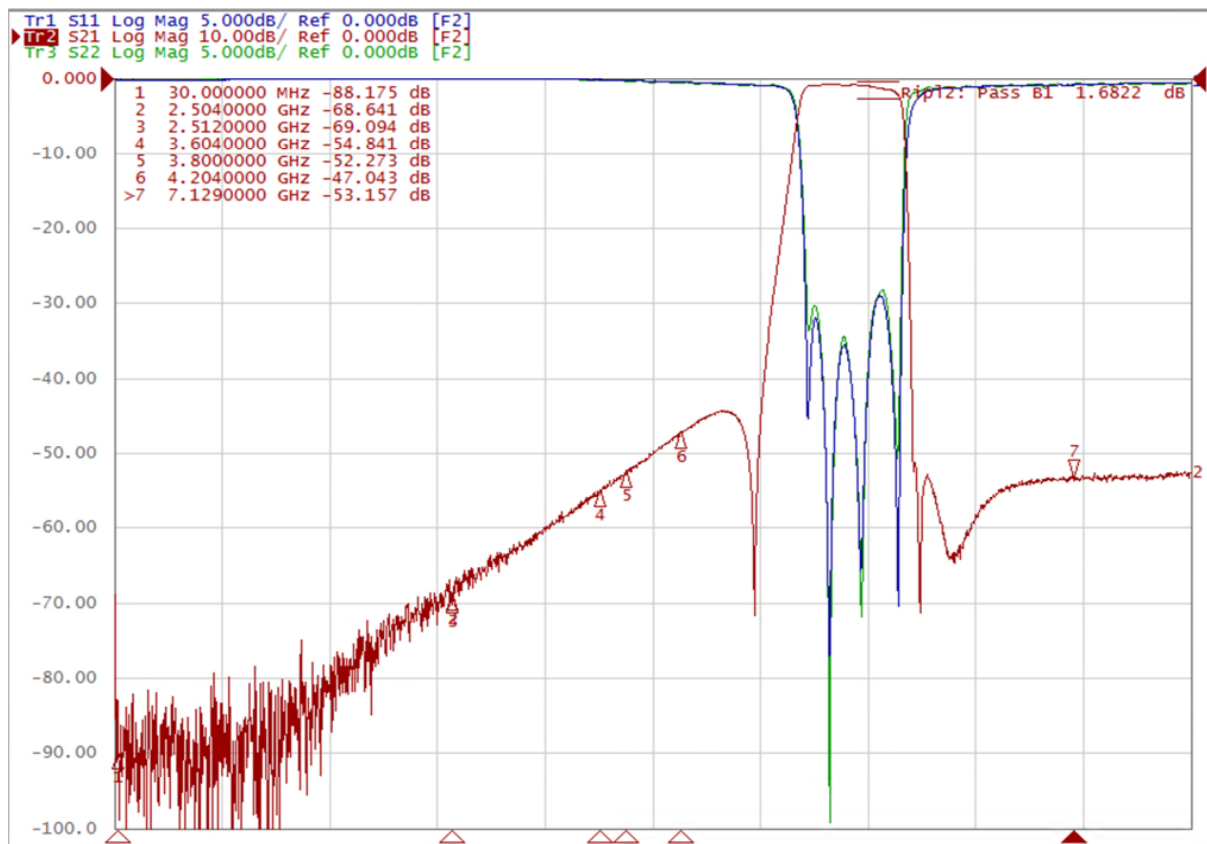
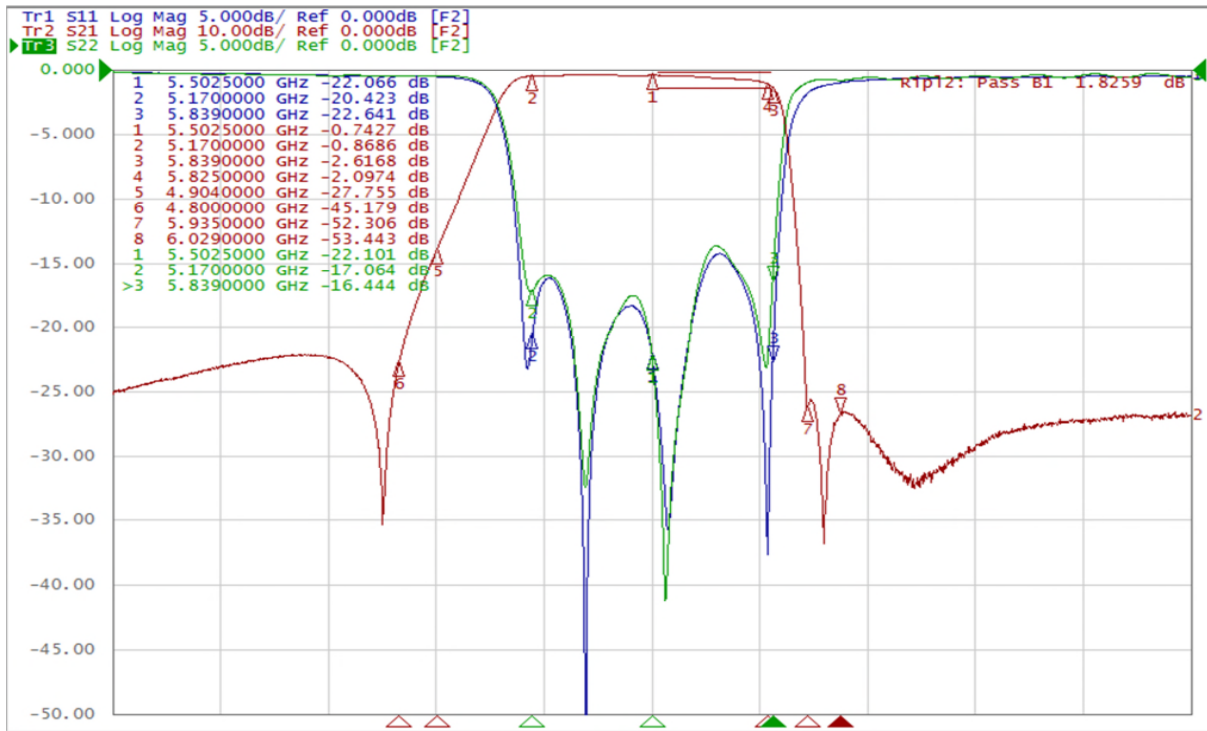
OUTLINE DRAWING



FOOTPRINT



ELECTRICAL CHARACTERISTICS CURVE



ABSOLUTE MAXIMUM RATINGS

Operation Temperature	-40°C to +95°C
Storage Temperature	-40°C to +95°C
Maximum Reflow Condition	≤+240°C (40-80s)
Max. Input Power	33dBm

NOTES

- RoHS 2.0/HSF
- Reflow soldering temperature curve

